

INTERNATIONAL STANDARD



**Semiconductor devices – Flexible and stretchable semiconductor devices –
Part 1: Bending test method for conductive thin films on flexible substrates**



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Part 1: Bending test method for conductive thin films on flexible substrates**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES – FLEXIBLE AND
STRETCHABLE SEMICONDUCTOR DEVICES –****Part 1: Bending test method for conductive
thin films on flexible substrates**

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The text of this International Standard is based on the following documents:

FDIS	Report on voting
47/2369/FDIS	47/2384/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62951 series, published under the general title *Semiconductor devices – Flexible and stretchable semiconductor devices*, can be found on the IEC website.

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SEMICONDUCTOR DEVICES – FLEXIBLE AND STRETCHABLE SEMICONDUCTOR DEVICES –

Part 1: Bending test method for conductive thin films on flexible substrates

1 Scope

This part of IEC 62951 specifies a bending test method to measure the electromechanical properties or flexibility of conductive thin films deposited or bonded on flexible non-conductive substrates. Conductive thin films on flexible substrates are extensively used in flexible electronic devices and flexible semiconductors. Conductive thin films include any films deposited or bonded onto a non-conductive flexible substrate such as thin metal film, transparent conducting electrode, and thin silicon film. The electrical and mechanical behaviours of thin films on flexible substrates differ from those of free standing films and substrates due to their interfacial interactions and adhesion between the film and substrate. The object of this standard is to establish simple and repeatable test methods for evaluating the electromechanical properties or flexibility of conductive thin films on flexible substrate. The bending test methods include outer bending test and inner bending test.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 62047-2:2006, *Semiconductor devices – Micro-electromechanical devices – Part 2: Tensile testing method of thin film materials*

IEC 62047-22:2014, *Semiconductor devices – Micro-electromechanical devices – Part 22: Electromechanical tensile test method for conductive thin films on flexible substrates*

3 Terms, definitions and symbols

3.1 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.1.1

bending radius of curvature

r

radius of curvature that the test piece shows in bending test